

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: :  
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Gobinda Das et al. :  
:   
Serial No.: Unassigned : Art Unit: 2858  
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Filed: January 4, 2002 : Examiner: Unassigned  
:   
For: TFI PROBE I/O WRAP TEST : Atty Docket: IBM: BUR990278US2  
METHOD : CBLH: 21806/0146

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

January 4, 2002

Sir:

Prior to initial examination, please amend the above-captioned case as follows.

**IN THE SPECIFICATION**

Please add the following heading and paragraph before line 5, page 1 of the Specification.

**-- CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a divisional application of co-pending U.S. application 09/615,198 by Gobinda Das et al., filed on July 13, 2000 for "TFI PROBE I/O WRAP TEST METHOD", the entire contents of which are hereby incorporated by reference, and for which priority is claimed under 35 U.S.C. §120. --

Please replace the paragraph beginning at line 9, page 12 of the Specification with the following replacement paragraph. No new matter has been presented by this amendment, which corrects an obvious typographical error in the cited patent number.

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--Modification to the TFI, see U.S. patent 5,207,585, issued May 4, 1993, to Byrnes et al., for Thin Interface Pellicle for Dense Arrays of Electrical Interconnects, the entire contents of the disclosure of which is hereby incorporated by reference, process to introduce the paired short may be relatively simple and can be implemented in several ways. The short metallurgy can be on either side of the probe bumps. Figs. 5a, 5b, 5c, and 5d depict process steps that may be utilized in forming a standard thin film interface. These process steps may be utilized to form a thin film interface structure according to the present invention as well, although with modifications.--

#### IN THE CLAIMS

Please cancel claims 1 through 13 without prejudice.

#### REMARKS

Claims 14 through 29 remain pending in this divisional application.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to IBM Deposit Account No. 09-0456 for any additional fees required, and the Commissioner is authorized to charge CBLH Deposit Account No. 22-0185 for extension of time fees.

Respectfully submitted,



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